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(72)Inventor: TOMIYAMA YASUYOSHI

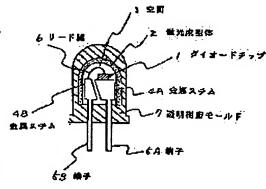
SHIRAISHI HIROYUKI ISHIWATARI MASAHARU

(54) INFRARED VISIBLE LIGHT CONVERSION LIGHT EMITTING DIODE OF SMALL DIRECTIVITY

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PURPOSE: To remarkably reduce directivity and make possible clear indication in the case of large size, by fixing a fluorescent molded object which dispersedly contains infrared visible light conversion phosphor, so as to keep a specified distance from an infrared light emitting diode.

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formed as a dome type fluorescent molded body 2, which is arranged so as to keep a specified distance from the diode chip 1. Thereby the directivity caused by the difference of luminance in the observation direction is reduced, so that clear indication can be obtained.

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(71)出願人 000006264

三菱マテリアル株式会社

東京都千代田区大手町1丁目5番1号

(72)発明者 富山 能省

埼玉県大宮市北袋町1丁目297番地 三菱

マテリアル株式会社中央研究所内

(72)発明者 白石 浩之

埼玉県大宮市北袋町1丁目297番地 三菱

マテリアル株式会社中央研究所内

(72)発明者 石渡 正治

埼玉県大宮市北袋町1丁目297番地 三菱

マテリアル株式会社中央研究所内

(54) 【発明の名称】 指向性の少ない赤外可視変換発光ダイオード

(57)【要約】

【目的】 指向性の少ない赤外可視変換発光ダイオード を提供する。

【構成】 赤外発光ダイオードの放射する赤外光を赤外 可視変換蛍光体を用いて可視光に変換して放射する赤外 可視変換発光ダイオードにおいて、赤外可視変換蛍光体 を分散含有するドーム状樹脂成型体を赤外発光ダイオー ドチップに対して所定の距離を設けて装着する。

【特許請求の範囲】

【請求項1】 赤外発光ダイオードの放射する赤外光を 赤外可視変換蛍光体を用いて可視光に変換して放射する 赤外可視変換発光ダイオードにおいて、赤外可視変換蛍 光体を分散含有するドーム状樹脂成型体を赤外発光ダイ オードチップに対して所定の距離を設けて装着してなる 指向性の少ない赤外可視変換発光ダイオード。

【発明の詳細な説明】

[0001]

【産業上の利用分野】この発明は、表示用などに広く用 10 いられている赤外可視変換発光ダイオード(以下、変換 発光ダイオードという)に関するものである。

[0002]

【従来の技術】従来、一般に変換発光ダイオードは赤外 発光部と赤外可視変換蛍光体含有樹脂層(以下、蛍光体 層という)とそれを覆う透明樹脂モールドよりなり、赤 外発光部は図2の概略断面図に示されるように赤外発光 ダイオードチップ1 (以下、ダイオードチップという) のN型層を金属ステム4Aに、同じくP型層をリード線 6を経て金属ステム4Bにボンディングしてなり、かつ 20 金属ステム4A、4Bは端子5A、5Bと一体のものか らなり、また前記蛍光体層8は赤外可視変換蛍光体 (以 下、変換蛍光体という)の粉末を分散含有するエポキシ 樹脂をダイオードチップ1に塗布することによって形成 され、赤外発光部と蛍光体層8が透明樹脂モールド7で パッケージされている。

【0003】また、上記変換発光ダイオードにおいて は、端子5Aと5Bの間に電圧を加えてダイオードチッ プ1のPN接合面の近傍からから赤外光を放射し、この 赤外光が上記の蛍光体層8を通過する間に変換蛍光体に 30 吸収されて特定波長の可視光に変換され透明樹脂モール ド7を通って外部へ放出される。

[0004]

【発明が解決しようとする課題】しかし、近年変換発光 ダイオードの大型化はめざましく、高い輝度を持つよう になったが、上記の従来変換発光ダイオードにおいては 蛍光体層が一般に塗布あるいは滴下などによってダイオ ードチップ上に形成されているので、均一な被着が困難 となるばかりでなく、この結果観察方向によって輝度が 異なるという指向性があらわれ、表示が不鮮明にならざ 40 るを得ないというのが現状である。

[0005]

【課題を解決するための手段】そこで、本発明者らは上 述のような観点から、大型化しても鮮明な表示の得られ る、指向性の少ない発光ダイオードを開発すべく研究を おこなった結果、上記従来発光ダイオードにおける蛍光 体層をドーム状の蛍光体成型体(以下、蛍光成型体とい う)とし、これをダイオードチップにたいして所定の距 離を散けて設置した構造とすると観察方向による輝度の 差に起因する指向性が少なくなって鮮明な表示が得られ 50 るという研究結果を得たのである。

【0006】この発明は、上記の研究結果にもとづいて なされたものであって、赤外発光ダイオードの放射する 赤外光を変換蛍光体を用いて可視光に変換して放射する 変換発光ダイオードにおいて、ダイオードチップに対し て所定の距離を設けて蛍光成型体を装着することにより 指向性を少なくした変換発光ダイオードに特徴を有する ものである。

[0007]

【実施例】次に、この発明の変換発光ダイオードを実施 例により具体的に説明する。表1に示される3種類の変 換蛍光体を同表 1 に示される割合でエポキシ樹脂に分散 混合し、これを外径3.0mm、高さ3.0mm、厚さ 0. 5mmの蛍光成型体とし、図1に見られるように前 述の従来変換発光ダイオードにおける発光部と同じ構造 を持つダイオードチップの上面にたいして1.0mmの 距離を離れて内面が位置するように蛍光成型体を設置 し、更に保護の目的で蛍光成型体を含む全体を透明樹脂 モールド7でパッケージすることにより本発明変換発光 ダイオード1~3をそれぞれ製造した。つぎに、この結 果得られた本発明変換発光ダイオード1~3について、 可視光の指向特性を評価する目的で端子5Aと5Bの間 に約1.2ボルトの電圧を加え20mAの順方向の電流 を流すことによってダイオードチップ1より赤外光を放 射し、可視光の強度を変換発光ダイオードの中心線に対 して30度の角度で透明樹脂モールド7の表面から30 cm離れた位置で、水平面上円周方向に沿って60度毎 に、光パワーメーターを用いて測定し、また前記中心線 を含む垂直面上で、ダイオードチップ1を中心点として 所定の傾斜角で測定し、中心線上で測定した強度を10 0として相対強度を算出し、この算出強度を表1に示し た。

【0008】比較の目的で図2に示されるとおり、蛍光 成型体に代わって平均厚さ0.5mmの蛍光体層を塗布 するとともに、空間の形成なくパッケージすること以外 は同一の条件で製造した従来変換発光ダイオード1~3 について同一の条件で可視光の強度を測定し同じく相対 強度を算出して表1に示した。

[0009]

【表1】

【0010】なお、本発明発光ダイオードにおいては赤 120度 ず、仕て、チェンを中心点とした傾回の角度 R ĸ ध 外光は透過するが可視光を反射する被膜で前記ドーム状 成型体の内面をコーティングしたり、同じく外面を可視 8 8 g 2 R 2 光は透過するが赤外光は反射する被膜でコーティング処 엻 理したりするとより一段と輝度を高めることが出来る。 8 ន ž, 8 8 2 さらに、発光部を保護するために蛍光成型体の内部を 異の 透明樹脂で充填してもよい。 æ 83 જ 8 ន ន [0011] 光音上 욢 욢 【発明の効果】 表1から明らかなように、本発明変換発 8 8 욢 8 300E 8 8 æ \$ **\$** 8

10 光ダイオード1~3は従来変換発光ダイオードに比して 観測の位置によるばらつきが著しく少なく均一な強度を 示し、極めて指向性が少なく、従って、大型にしても鮮 明な表示が可能となるなど工業上有用な特性を有する。

【図面の簡単な説明】

【図1】 本発明変換発光ダイオードの断面図 【図2】 従来変換発光ダイオードの断面図 【符号の説明】

- 1. ダイオードチップ
- 2. 蛍光成型体
- 20 3. 空間
 - 4A. 4B. 金属ステム
 - 5A. 5B. 端子
 - 6. リード線
 - 7. 透明樹脂モールド
 - 蛍光体層

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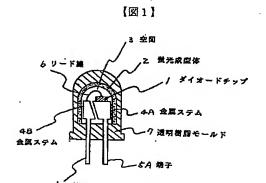
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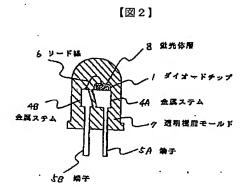
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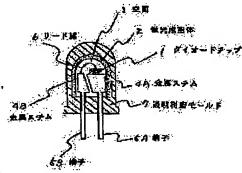
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CONSTITUTION: A fluorescent molded object 2 is arranged in the manner in which the inner surface is positioned so as to keep a specified distance, e.g. 1.0mm, from the upper surface of a diode chip 1. For the purpose of protection, the whole part containing the fluorescent molded object 2 is packaged by using a transparent resin mold 7, and conversion light emitting diodes 1–3 are manufactured. A phosphor layer is formed as a dome type fluorescent molded body 2, which is arranged so as to keep a specified distance from the diode chip 1. Thereby the directivity caused by the difference of luminance in the observation direction is reduced, so that clear indication can be obtained.



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CLAIMS

[Claim(s)]

[Claim 1]In an infrared visible conversion light emitting diode which changes and emits infrared light which an infrared emitting diode emits to visible light using an infrared visible conversion fluorescent substance, Few directive infrared visible conversion light emitting diodes which establish a predetermined distance and equip with a dome state resin molded body which carries out distributed content of the infrared visible conversion fluorescent substance to an infrared light emitting diode chip.

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DETAILED DESCRIPTION

[Detailed Description of the Invention]

[0001]

[Industrial Application] This invention relates to the infrared visible conversion light emitting diode (henceforth a conversion light emitting diode) widely used for the display.
[0002]

[Description of the Prior Art]Generally conventionally a conversion light emitting diode An infrared light-emitting part and an infrared visible conversion fluorescent substance content resin layer. It becomes (calling it a fluorescent substance layer hereafter) from a wrap transparent resin mold about it, As shown in the outline sectional view of <u>drawing 2</u>, an infrared light-emitting part The infrared light emitting diode chip 1. Similarly bonding of the P type layer is carried out for the N type layer of (calling it a diode chip hereafter) to the metal stem 4A through the lead 6 at the metal stem 4B, And the metal stems 4A and 4B consist of a thing of the terminals 5A and 5B and one, Said fluorescent substance layer 8 is formed by applying to the diode chip 1 the epoxy resin which carries out distributed content of the powder of an infrared visible conversion fluorescent substance (henceforth a conversion fluorescent substance), and the infrared light-emitting part and the fluorescent substance layer 8 are packed by the transparent resin mold 7.

[0003]In the above-mentioned conversion light emitting diode, among the terminals 5A and 5B, apply voltage and the ** side of the PN-junction side of the diode chip 1 emits infrared light clitteringly, While this infrared light passes the above-mentioned fluorescent substance layer 8, it is absorbed by the conversion fluorescent substance, is changed into the visible light of a specified wavelength, and is emitted to the exterior through the transparent resin mold 7. [0004]

[Problem(s) to be Solved by the Invention]However, although enlargement of a conversion light emitting diode is remarkable in recent years and it came to have high luminosity, Since the fluorescent substance layer is generally formed by spreading or dropping on the diode chip in the above-mentioned conventional conversion light emitting diode, The actual condition is that uniform covering not only becomes difficult, but the directivity that luminosity differs cannot but appear and a display cannot but become indistinct by an observation direction as a result. [0005]

[Means for Solving the Problem]. Then, a clear display is obtained even if this invention persons enlarge from the above viewpoints. A result of having inquired few directive light emitting diodes being developed, A fluorescent substance layer in a light emitting diode conventionally [above—mentioned] A fluorescent substance molding body of dome state. It presupposed (it is hereafter called a fluorescence molding body), and when it was the structure which provided so predetermined a distance in a diode chip, and installed this in it, a research result that directivity resulting from a difference of luminosity by an observation direction decreased, and a clear display was obtained was obtained.

[0006]In a conversion light emitting diode which this invention is made based on the above-mentioned research result, and changes and emits infrared light which an infrared emitting diode emits to visible light using a conversion fluorescent substance, It has the feature in a conversion

light emitting diode which lessened directivity by establishing a predetermined distance to a diode chip and equipping with a fluorescence molding body.

[0007]

[Example] Next, an example explains the conversion light emitting diode of this invention concretely. Dispersion mixing of three kinds of conversion fluorescent substances shown in Table 1 is carried out to an epoxy resin at a rate shown in the table 1, This is made into a fluorescence molding body (the outer diameter of 3.0 mm, 3.0 mm in height, and 0.5 mm in thickness), A fluorescence molding body is installed so that the distance of 1.0 mm may be left so much on the upper surface with the structure same so that drawing 1 may see as the lightemitting part in the above-mentioned conventional conversion light emitting diode of a diode chip and an inner surface may be located, this invention conversion light emitting diodes 1-3 were manufactured, respectively by packing the whole which contains a fluorescence molding body for the purpose of protection by the transparent resin mold 7. Next, about this invention conversion light emitting diodes 1-3 obtained as a result. Infrared light is emitted from the diode chip 1 by applying the voltage of about 1.2 volts among the terminals 5A and 5B in order to evaluate the directional characteristics of visible light, and sending the current of a 20-mA forward direction, In the position which is distant from the surface of the transparent resin mold 7 30 cm at the angle of 30 degrees to the center line of a conversion light emitting diode, visible luminous intensity. Along with the level surface top circumferencial direction, every 60 degrees, on the vertical plane which measures using a light power meter and includes said center line, relative intensity was computed by having set to 100 intensity which was measured with the predetermined angle of inclination by having made the diode chip 1 into the central point, and was measured on the center line, and this calculation intensity was shown in Table 1. [0008]While applying a fluorescent substance layer with an average thickness of 0.5 mm instead of a fluorescence molding body as shown in drawing 2 for the comparative purpose, Except packing without formation of space, visible luminous intensity was measured on the conditions conventionally same about the conversion light emitting diodes 1-3 manufactured on the same conditions, similarly relative intensity was computed, and it was shown in Table 1. [0009]

[Table 1]

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[0010]Although the inner surface of said dome state molding body is coated with the tunic which reflects visible light although infrared light penetrates in this invention light emitting diode or visible light similarly penetrates an outside surface, if coating treatment of the infrared light is carried out with the tunic to reflect, it can raise luminosity much more. In order to protect a light-emitting part, the inside of a fluorescence molding body may be filled up with transparent resin.

[0011]

[Effect of the Invention]this invention conversion light emitting diodes 1-3 show little uniform intensity with remarkable dispersion by the position of observation as compared with a conversion light emitting diode conventionally so that clearly from Table 1, and even if directivity makes it large-sized few therefore extremely, that a clear display is attained etc. has the useful

characteristic on industry.

[Translation done.]

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DESCRIPTION OF DRAWINGS

[Brief Description of the Drawings]

[Drawing 1] The sectional view of this invention conversion light emitting diode [Drawing 2] The sectional view of the conventional conversion light emitting diode [Description of Notations]

1. Diode chip

- 2. Fluorescence molding body
- 3. Space

4A.4B. Metal stem

5A.5B. Terminal

- 6. Lead
- 7. Transparent resin mold
- 8. Fluorescent substance layer

[Translation done.]